## **AMENDMENTS TO THE CLAIMS**

- 1. (Original) A thermosetting resin composition, which comprises the following (A) component and (B) component.
- (A) component: at least one kind of phenol resin selected from the group consisting of alkylphenol novolak, a phenol adduct of an aliphatic polymer containing a double bond, and a phenol adduct of an alicyclic polymer containing a double bond
- (B) component: epoxy group containing ethylene copolymer obtained by polymerizing the following (b<sub>1</sub>) and (b<sub>2</sub>):
  - (b<sub>1</sub>) ethylene and/or propylene
  - (b<sub>2</sub>) monomer represented by the following formula (1):

$$R \xrightarrow{X} O \xrightarrow{CH_2} CH \xrightarrow{CH_2} (1)$$

(wherein R represents a hydrocarbon group of a carbon number of from 2 to 18 having a double bond, wherein at least one of hydrogen atoms of the hydrocarbon group may be substituted with a halogen atom, a hydroxyl group or a carboxyl group, and X represents a single bond or a carbonyl group.)

2. (Original) The thermosetting resin composition according to claim 1, wherein the alkylphenol novolak is a condensate of formalin and phenol substituted with an alkyl group of a carbon number of from 2 to 20.

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3. (Original) The thermosetting resin composition according to claim 1, wherein a content

of a structural unit derived from (b<sub>2</sub>) is from 1 to 30 parts by weight relative to 100 parts by

weight of (B) component.

4. (Original) The thermosetting resin composition according to claim 1, wherein the (B)

component is a copolymer obtained by polymerizing  $(b_1)$ ,  $(b_2)$  and the following  $(b_3)$ :

(b<sub>3</sub>): a monomer which has a functional group copolymerizable with ethylene, has no

functional group reactive with an epoxy group, and is different from either of (b<sub>1</sub>) and (b<sub>2</sub>).

5. (Original) The thermosetting resin composition according to claim 1, wherein a content

of a structural unit derived from (b<sub>1</sub>) is from 30 to 75 parts by weight relative to 100 parts by

weight of the (B) component.

6. (Original) The thermosetting resin composition according to claim 1, wherein a weight

ratio of the (A) component and the (B) component is (A)/(B)=4/96 to 50/50.

7. (Original) The thermosetting resin composition according to claim 1, which further

contains (C) component:

(C) component: antioxidant.

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8. (Original) The thermosetting resin composition according to claim 7, wherein the (C) component is at least one of an antioxidant selected from the group consisting of a phenolic antioxidant, a phosphoric antioxidant and a sulfuric antioxidant.

- 9. (Original) An adhesive, which contains the thermosetting resin composition as defined in claim 1 and the following (D) component:
  - (D): organic solvent and/or water.
- 10. (Original) The adhesive according to claim 9, wherein a total weight of the (A) component and the (B) component is from 10 to 150 parts by weight relative to 100 parts by weight of the (D) component.
- 11. (Original) An adhesive film, which contains the thermosetting resin composition as defined in claim 1.
- 12. (Currently Amended) The An adhesive film according to claim 11, which is obtained by coating the adhesive as defined in claim 9 on a support substrate, and drying this.
- 13. (Original) The adhesive film according to claim 11, which is obtained by extrusion molding.

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14. (Original) An adhesive film, which is obtainable by further irradiating the adhesive film as defined in claim 11 with an electron beam.

- 15. (Original) The adhesive film according to claim 14, which is obtainable by performing electron beam irradiation plural times.
- 16. (Original) A laminate, which is obtainable by laminating the adhesive film as defined in claim 11 or 14 and an adherend, and thermally curing this.